PRODUCT DATA SHEET

NC-SMQ®51C

Solder Paste

Introduction

NC-SMQ®51C is an air reflow, no-clean solder paste designed for use in a wide range of environmental conditions. It has exceptional stencil life and tack strength, and offers consistent print definition—even in ultra-fine pitch applications. **NC-SMQ®51C**'s wide processing window allows it to be used with standard eutectic SnPb, SnPbAg, and SnAgCu alloys.

Features

- Wide reflow process window
- Consistent fine-pitch print deposition
- Superior tack strength
- No-clean residue
- Exceptional wetting in air reflow

Alloys

Indium Corporation manufactures low-oxide spherical solder powder composed of SnPb and SnPbAg in a standard Type 3 mesh size (J-STD-006). Other non-standard mesh sizes are available upon request. The weight ratio of the solder powder to solder paste is referred to as the metal load and is typically in the range of 82–91% for standard alloy compositions.

Standard Product Specifications

Alloy	Metal Load (% by weight)		Powder Type
	Printing	Dispensing	
Sn63 Sn62	90–90.5	83–85	Type 3

Compatible Products

- Rework Flux: TACFlux®007
- Cored Wire: CW-807
- Wave Flux: WF-9945, WF-9955

Note: Other products may be applicable. Please consult one of Indium Corporation's Technical Support Engineers.

Storage and Handling Procedures

Refrigerated storage will prolong the shelf life of solder paste. Solder paste packaged in cartridges should be stored tip down.

Storage Conditions (unopened containers)	Shelf Life
<10°C	6 months

Solder paste should be allowed to reach ambient working temperature prior to use. Generally, paste should be removed from refrigeration at least 2 hours before use. Actual time to reach thermal equilibrium will vary with container size. Paste temperature should be verified before use. Jars and cartridges should be labeled with date and time of opening.

Cleaning

NC-SMQ®51C is designed for no-clean applications. However, the flux can be removed, if necessary, by using a commercially available flux residue remover.

Stencil cleaning is best performed using isopropyl alcohol (IPA) as a solvent. Most commercially available non-water-based stencil cleaners work well.

Safety Data Sheets

The SDS for this product can be found online at http://www.indium.com/sds

Industry Standard Test Results and Classification			
Flux Classification	ROL1	Typical Solder Paste Viscosity for Sn63 T3 (Poise)	2,000
Based on the testing required by the current revision of IPC J-STD-004.		Conforms with all requirements from the current revision of IPC J-STD-005.	

All information is for reference only. Not to be used as incoming product specifications.

From One Engineer To Another®

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Printing

Stencil Design:

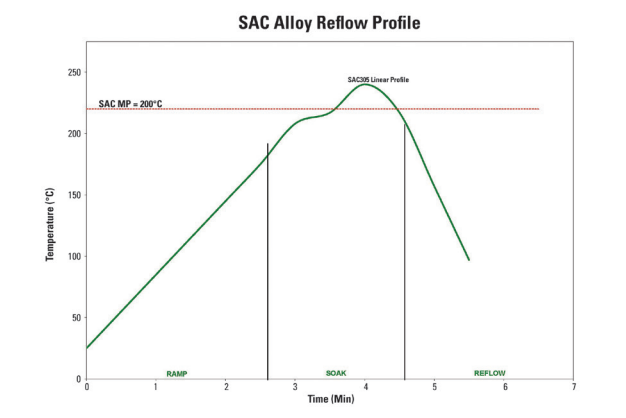
Electroformed and laser cut/electropolished stencils produce the best printing characteristics among stencil types. Stencil aperture design is a crucial step in optimizing the print process. The following are a few general recommendations:

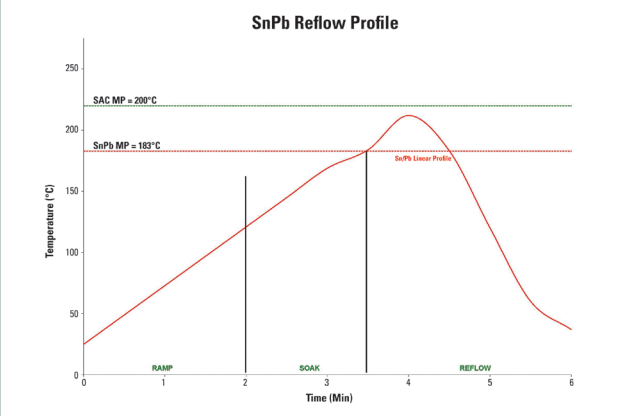
- Discrete components—A 10–20% reduction of stencil aperture has significantly reduced or eliminated the occurrence of mid-chip solder beads. The "home plate" design is a common method for achieving this reduction.
- Fine-pitch components—A surface area reduction is recommended for apertures of 20mil pitch and finer. This reduction will help minimize solder balling and bridging that can lead to electrical shorts. The amount of reduction necessary is process dependent (5–15% is common).
- For optimum transfer efficiency and release of the solder paste from the stencil apertures, industry standard aperture and aspect ratios should be adhered to.

Printer Operation	
Solder Paste Bead Size	~20–25mm in diameter
Print Speed	25–50mm/second
Squeegee Pressure	0.018–0.027Kg/mm of blade length
Underside Stencil Wipe	Start at once per every 10–25 prints and decrease frequency until optimum value is reached
Squeegee Type/Angle	Metal with appropriate length/60 degrees
Separation Speed	5–20mm/second or per equipment manufacturer's specifications
Solder Paste Stencil Life	>8 hrs. (at 30–60% RH and 22–28°C)

Reflow

Recommended Profile:





Profile Details	Parameters			Comments
	SAC305	SAC305/Sn63/Sn62	Sn63/Sn62	
Ramp Profile (Average Ambient to Peak)—Not the Same as Maximum Rising Slope	0.5–1°C/Second Recommended 0.5–2.5°C/Second Acceptable			To minimize solder balling, beading, hot slump
Soak Zone Profile	160–180°C/Recommended 150–200°C/Acceptable	30–90 Seconds Recommended 30–120 Seconds Acceptable	140–150°C/Recommended 130–170°C/Acceptable	May minimize BGA/CSP voiding
Time Above Liquidus (TAL)	235–250°C/Recommended 232–270°C/Acceptable	45–60 Seconds Recommended 30–100 Seconds Acceptable	198–213°C/Recommended 195–233°C/Acceptable	Needed for good wetting/reliable solder joint
Peak Temperature	260°C	—	230°C	As measured with thermocouple
Cooling Ramp Rate	2–6°C/Second Recommended 0.5–6°C/Second Acceptable			Rapid cooling promotes fine-grain structure
Reflow Atmosphere	Air or N_2			N_2 can aid with material performance

Note: All parameters are for reference only. Modifications may be required to fit process and design.

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